



H432 Series

ADJUSTABLE SHUNT REGULATOR

Description

The H432 series are three-terminal adjustable regulators with guaranteed thermal stability over applicable temperature ranges. The output voltage may be set to any value between V_{REF} (approximately 1.24 or 1.25 volts) and 30 volts with two external resistors. These devices have a typical dynamic output impedance of 0.2Ω . Active output circuitry provides a very sharp turn-on characteristic, making these devices excellent replacement for zener diodes in many applications.

Features

- Programmable output voltage
- Temperature coefficient is 50ppm/°C typical
- Temperature compensated for operation over full temperature range
- Low output noise voltage
- Fast turn on response

Ordering Information

Package	V_{REF} 1.24V±2%	V_{REF} 1.24V±1%	V_{REF} 1.24V±0.5%	V_{REF} 1.25V±2%	V_{REF} 1.25V±1%	V_{REF} 1.25V±0.5%
SOT-23	H432AN	H432BN	H432CN	H432DN	H432EN	H432FN
SOT-89	H432AM	H432BM	H432CM	H432DM	H432EM	H432FM
TO-92	H432AA	H432BA	H432CA	H432DA	H432EA	H432FA

Absolute Maximum Ratings

(Operating temperature range applies unless otherwise specified)

Characteristics	Symbol	Value		Unit
Cathode Voltage	V_{KA}	30		V
Cathode Current Range (Continuous)	I_K	50		mA
Reference Input Current Range	I_{REF}	0.05~+10		mA
Power Dissipation	P_D	SOT-23	280	mW
		SOT-89	770	
		TO-92	770	
Operating Temperature Range	T_{opr}	0~+70		°C
Junction Temperature	T_J	150		°C
Storage Temperature Range	T_{stg}	-65~+150		°C

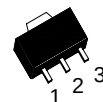
Operating Conditions

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Cathode Voltage	V_{KA}	V_{REF}	-	30	V
Cathode Current Range (Continuous)	I_K	1	10	-	mA

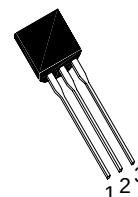
H432 Series Pin Assignment



3-Lead Plastic **SOT-23**
Package Code: N
Pin 1: Reference
Pin 2: Cathode
Pin 3: Anode



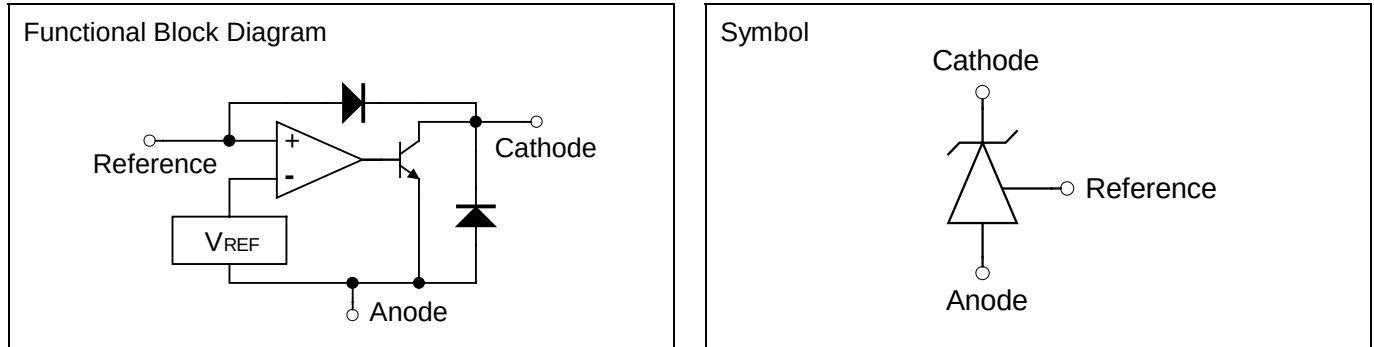
3-Lead Plastic **SOT-89**
Package Code: M
Pin 1: Reference
Pin 2: Anode
Pin 3: Cathode



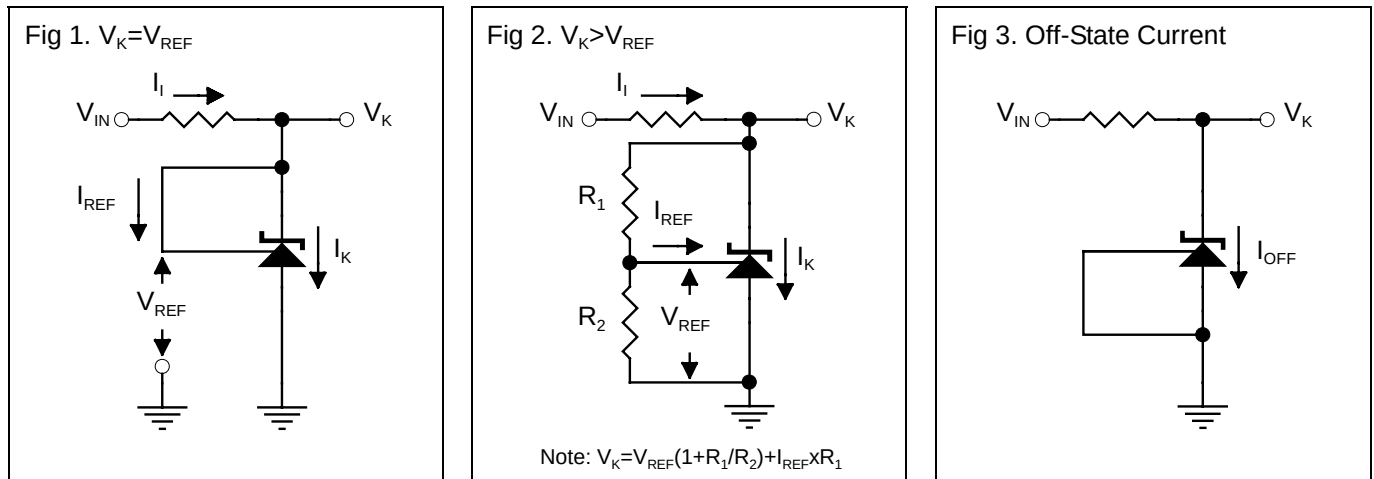
3-Lead Plastic **TO-92**
Package Code: A
Pin 1: Reference
Pin 2: Anode
Pin 3: Cathode



Functional Block Diagram & Symbol



Test Circuits

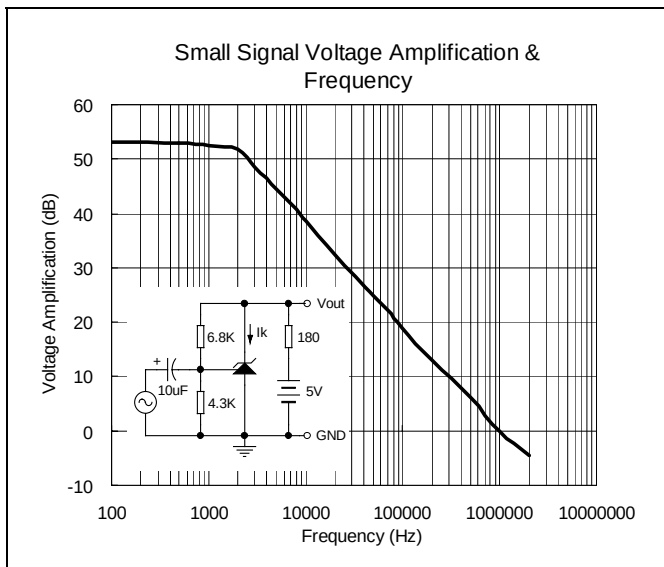
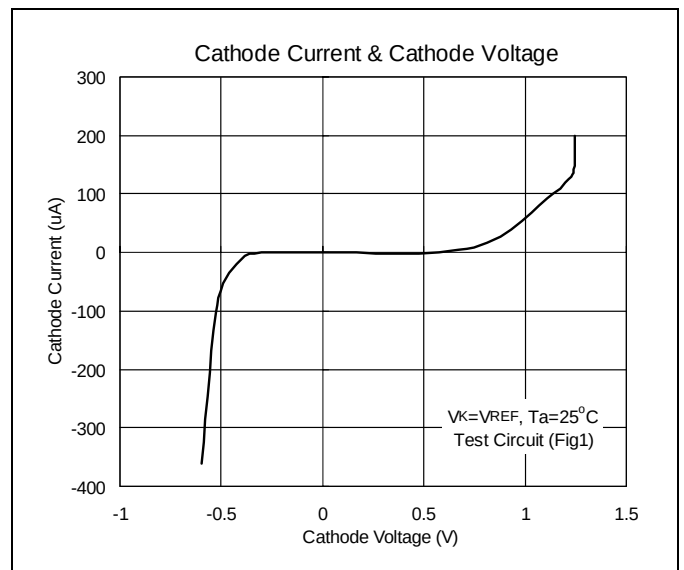
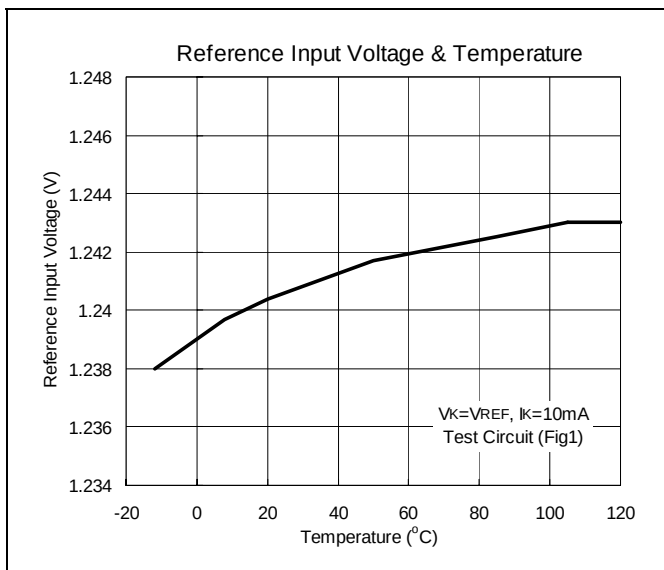
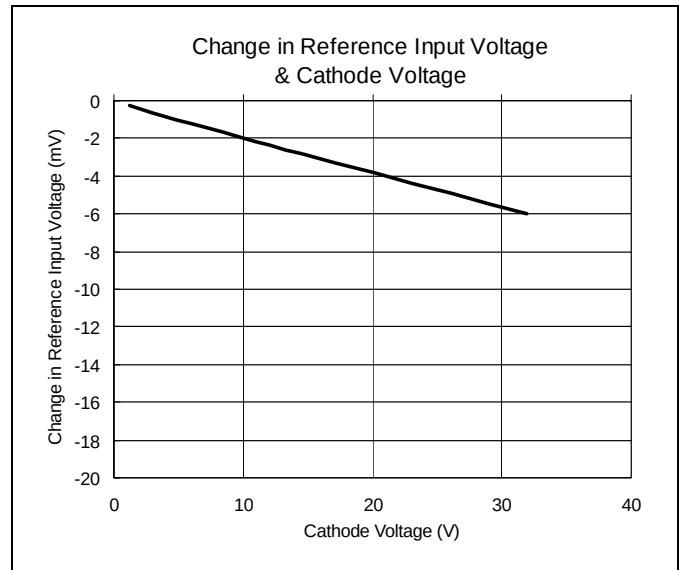
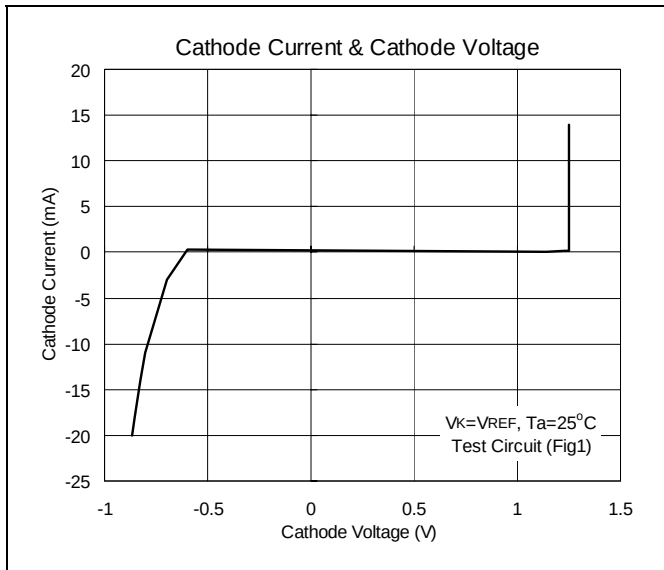


Electrical Characteristics (Ta=25°C unless otherwise specified)

Characteristics		Symbol	Test Conditions	Min	Typ	Max	Unit
Reference Input Voltage (Fig1)	H432AN/AM/AA	V_{REF}	$V_K = V_{REF}, I_K = 10mA$	1.215	1.24	1.265	V
	H432BN/BM/BA			1.228	1.24	1.252	
	H432CA/CM/CA			1.234	1.24	1.246	
	H432DN/DM/DA			1.225	1.25	1.275	
	H432EN/EM/EA			1.238	1.25	1.262	
	H432FN/FM/FA			1.244	1.25	1.256	
Deviation of Reference Input Voltage Over-Temperature (Fig1)		$V_{REF(dev)}$	$V_K = V_{REF}, I_K = 10mA$ $T_{min} \leq T_a \leq T_{max}$	-	4	17	mV
Ratio of Change in Reference Input Voltage to the Change in Cathode Voltage (Fig2)		$\Delta V_{REF} / \Delta V_K$	$I_K = 10mA,$ $\Delta V_K = 10V \text{ to } V_{REF}$	-	-1.4	-2.7	mV/V
			$I_K = 10mA,$ $\Delta V_K = 30V \text{ to } 10V$	-	-1	-2	mV/V
Reference Input Current (Fig2)		I_{REF}	$I_K = 10mA, R_1 = 10k\Omega,$ $R_2 = \infty$	-	1	4	μA
Deviation of Reference Input Current Over Full Temperature Range (Fig2)		$I_{REF(dev)}$	$I_K = 10mA, R_1 = 10k\Omega,$ $R_2 = \infty, T_a = \text{Full Range}$	-	0.4	1.2	μA
Minimum Cathode Current for Regulation (Fig1)		$I_{K(min)}$	$V_K = V_{REF}$	-	0.4	1	mA
Off-State Cathode Current (Fig3)		$I_{K(off)}$	$V_K = 30V, V_{REF} = 0$	-	0.1	1	μA



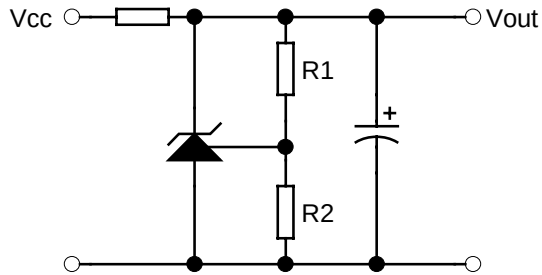
Characteristics Curve





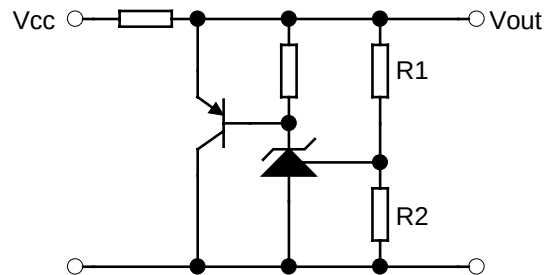
Typical Application

Fig 4. Shunt Regulator



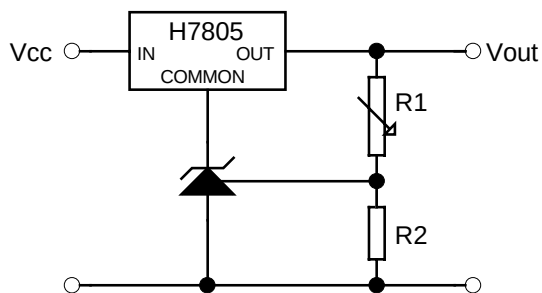
$$V_{out} = (1 + R_1/R_2)V_{REF}$$

Fig 5. High Current Shunt Regulator



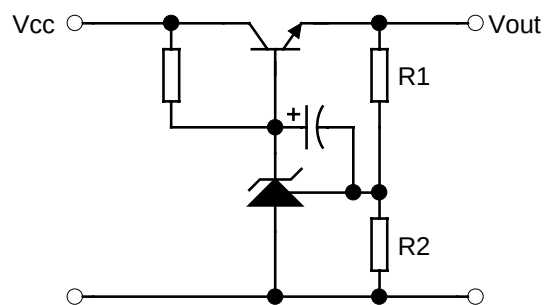
$$V_{out} = (1 + R_1/R_2)V_{REF}$$

Fig 6. Output Control of a Three-Terminal Fixed Regulator



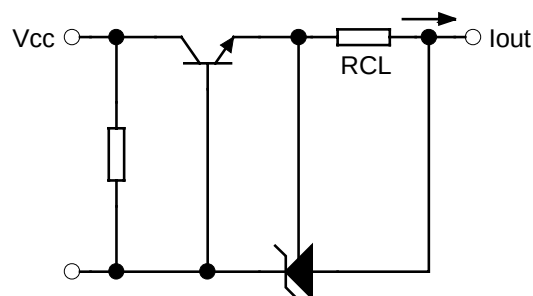
$$V_{out} = (1 + R_1/R_2)V_{REF}; V_{out(min)} = V_{REF} + 5V$$

Fig 7. Series Pass Regulator



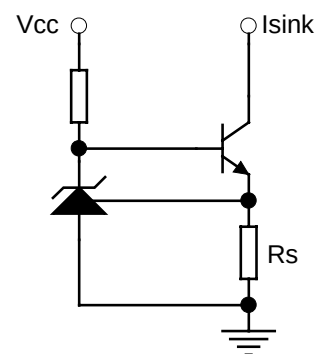
$$V_{out} = (1 + R_1/R_2)V_{REF}; V_{out(min)} = V_{REF} + V_{BE}$$

Fig 8. Current Limiter or Current Source



$$I_{out} = V_{REF}/R_{CL}$$

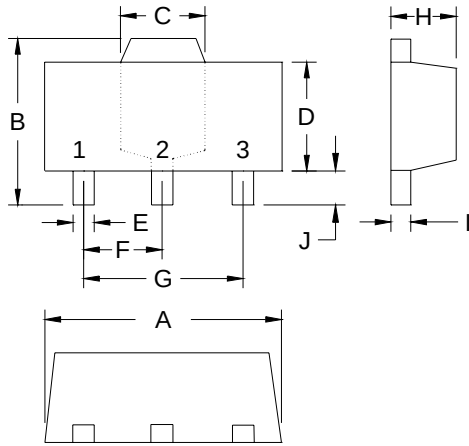
Fig 9. Constant Current Sink



$$I_{sink} = V_{REF}/R_S$$

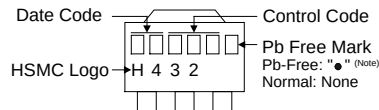


SOT-89 Dimension



3-Lead SOT-89 Plastic
Surface Mounted Package
HSMC Package Code: M

Marking:



Note: Green label is used for pb-free packing

Pin Style: 1.Reference 2.Anode 3.Cathode

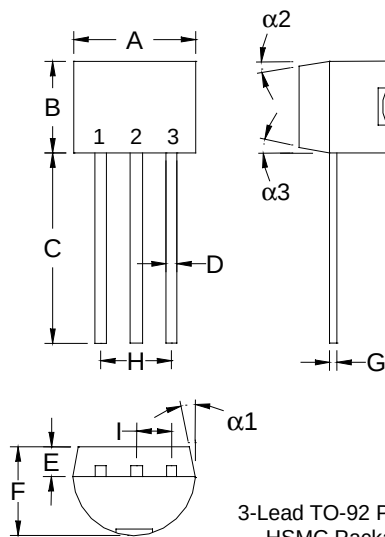
Material:

- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	4.40	4.60
B	4.05	4.25
C	1.50	1.70
D	2.40	2.60
E	0.36	0.51
F	*1.50	-
G	*3.00	-
H	1.40	1.60
I	0.35	0.41

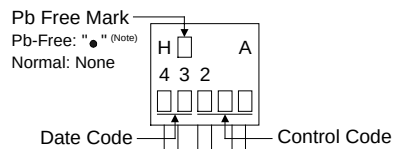
*: Typical, Unit: mm

TO-92 Dimension



3-Lead TO-92 Plastic Package
HSMC Package Code: A

Marking:



Note: Green label is used for pb-free packing

Pin Style: 1.Reference 2.Anode 3.Cathode

Material:

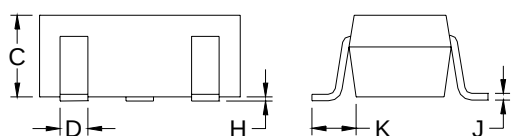
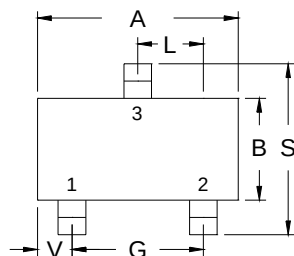
- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	4.33	4.83
B	4.33	4.83
C	12.70	-
D	0.36	0.56
E	-	*1.27
F	3.36	3.76
G	0.36	0.56
H	-	*2.54
I	-	*1.27
$\alpha 1$	-	*5°
$\alpha 2$	-	*2°
$\alpha 3$	-	*2°

*: Typical, Unit: mm

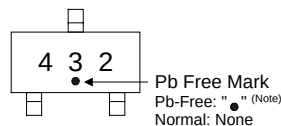


SOT-23 Dimension



3-Lead SOT-23 Plastic
Surface Mounted Package
HSMC Package Code: N

Marking:



Note: Pb-free product can distinguish by the green label or the extra description on the right side of the label.

Pin Style: 1.Reference 2.Cathode 3.Anode

Material:

- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	2.80	3.04
B	1.20	1.60
C	0.89	1.30
D	0.30	0.50
G	1.70	2.30
H	0.013	0.10
J	0.085	0.177
K	0.32	0.67
L	0.85	1.15
S	2.10	2.75
V	0.25	0.65

*: Typical, Unit: mm

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory:

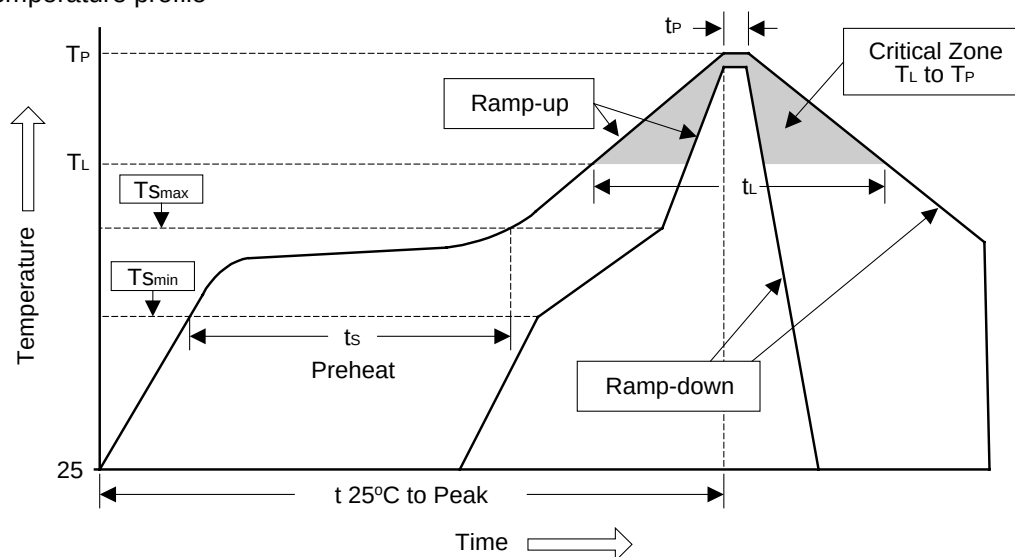
- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel: 886-3-5983621~5 Fax: 886-3-5982931



Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T_{Smin})	100°C	150°C
- Temperature Max (T_{Smax})	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
T_{Smax} to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec